

MIC3490

High Input Voltage, Low I_O µCap LDO Regulator

Features

- Wide Input Voltage Range: 2.3V to 36V
- Ultra-Low Ground Current: 18 µA
- · Low Dropout Voltage of 270 mV at 100 mA
- High Output Accuracy of ±2.0% Overtemperature
- µCap: Stable with Ceramic or Tantalum Capacitors
- Excellent Line and Load Regulation Specifications
- Near Zero Shutdown Current: Typical 0.1 µA
- Reverse Battery Protection
- Reverse Leakage Protection
- Thermal Shutdown and Current-Limit Protection
- SOT23-5 Package
- The MIC3490 is Pin-to-Pin Compatible with LM3940

Applications

- Keep-Alive Supply in Notebook and Portable Computers
- USB Power Supply
- · Logic Supply for High-Voltage Batteries
- · Automotive Electronics
- · Battery-Powered Systems
- 3 to 4-Cell Li-Ion Battery Input Range

General Description

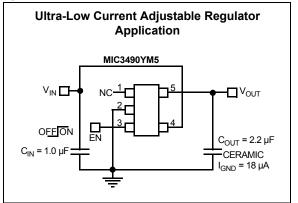
The MIC3490 is a 100 mA, highly accurate, low-dropout regulator with high input voltage and ultra-low ground current. This combination of high voltage and low ground current makes the MIC3490 ideal for multi-cell Li-lon battery systems.

As a μ Cap LDO design, the MIC3490 is stable with either ceramic or tantalum output capacitors. It only requires a 2.2 μ F output capacitor for stability.

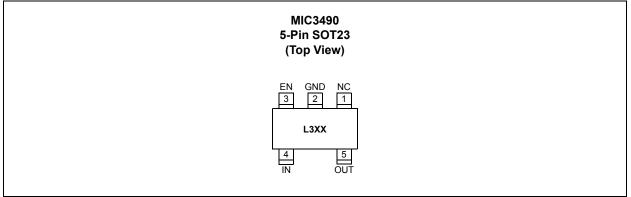
Features of the MIC3490 include enable input, thermal shutdown, current limit, reverse battery protection and reverse leakage protection.

Available in five output voltage options (1.8V, 2.5V, 3.0V, 3.3V and 5.0V), the MIC3490 is offered in a 5-pin SOT23 package with a junction temperature range of -40° C to + 125°C.

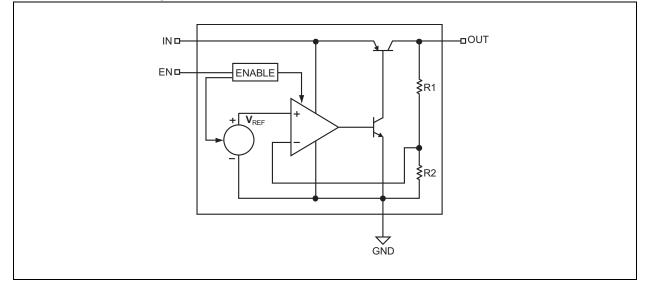
Typical Application Circuit



Package Types



Functional Block Diagrams



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Input Supply Voltage (V _{IN})	-20V to +38V
Enable Input Voltage (V _{FN})	-0.3V to +38V
Power Dissipation (P _{DIS})	Internally Limited
ESD Rating (Note 1)	ESD Sensitive

Operating Ratings ‡

Input Supply Voltage (VIN)+	2.3V to +36V
Enable Input Voltage (V _{EN})	0V to +36V

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability. Specifications are for packaged product only.

‡ Notice: The device is not ensured to function outside its operating ratings.

Note 1: Devices are ESD sensitive. Handling precautions are recommended.

TABLE 1-1: ELECTRICAL CHARACTERISTICS

Electrical Characteristics: T_J = +25°C with V_{IN} = V_{OUT} + 1V; I_{OUT} = 100 μ A;

Bold values indicate $-40^{\circ}C \le T_{J} \le +125^{\circ}C$; unless otherwise specified. Specifications for packaged product only.

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions	
Output Voltage Assures	V	-1.0	—	1.0	%	Variation from nominal V	
Output Voltage Accuracy	V _{OUT}	-2.0	—	2.0	70	Variation from nominal V _{OUT}	
Line Regulation	$\Delta V_{OUT} / \Delta V_{IN}$	_	0.04	0.5	%	$V_{IN} = V_{OUT} + 1V \text{ to } 36V$	
Load Regulation	ΔV _{OUT} /V _{OUT}	_	0.25	1	%	I _{OUT} = 100 μA to 100 mA	
		_	50			I _{OUT} = 100 μA	
		_	230	300		I _{OUT} = 50 mA	
Dropout Voltage	V _{DO}	_	_	400	mV		
			270	400		I _{OUT} = 100 mA	
				450			
Ground Current	I _{GND}		18	30		1001	
				35	μA	Ι _{ΟUT} = 100 μΑ	
			0.25	0.70		I _{OUT} = 50 mA	
		_	1	2	mA	I _{OUT} = 100 mA	
Ground Current in Shutdown	I _{SHDN}	_	0.1	1	μA	V _{EN} ≤ 0.6V; V _{IN} = 36V	
Short-Circuit Current	I _{SC}		190	350	mA	V _{OUT} = 0V	
Output Leakage, Reverse Polarity Input (Note 2)	V _{OUT}	_	-0.1	—	V	Load = 500Ω; V _{IN} = -15V	
Enable Input	· ·						
Input Low Voltage				0.6	N	Regulator off	
Input High Voltage	V _{EN}	2.0	_		V	Regulator on	
		-1.0	0.01	1.0		V _{EN} = 0.6V; Regulator off	
Enable Input Current	I _{EN}		0.1	1.0	μA	V _{EN} = 2.0V; Regulator on	
		_	0.5	2.5	1	V _{EN} = 36V; Regulator on	
Start-up Time	t _{START}		1.7	7	ms	V _{IN} applied before EN signal	

TEMPERATURE SPECIFICATIONS⁽¹⁾

Parameters		Min.	Тур.	Max.	Units	Conditions
Temperature Ranges						
Junction Operating Temperature Range	TJ	-40	—	+125	°C	—
Storage Temperature Range		-65	_	+150	°C	—
Package Thermal Resistances						
Thermal Resistance 5-Pin SOT23	θ_{JA}	_	235	_	°C/W	—

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.

2: Design guidance only, not production tested.

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

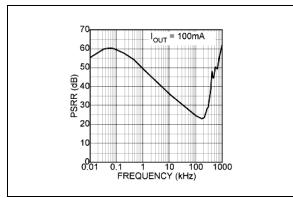


FIGURE 2-1: Power Supply Rejection Ratio.

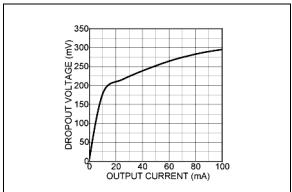
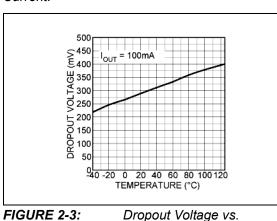


FIGURE 2-2: Current.

Dropout Voltage vs. Output



Temperature.

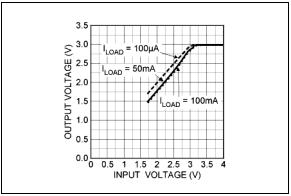


FIGURE 2-4: Dropout Characteristics.

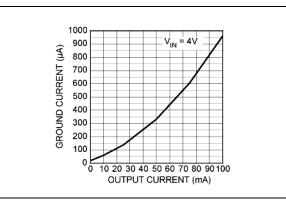


FIGURE 2-5: Output Current.

Ground Pin Current vs.

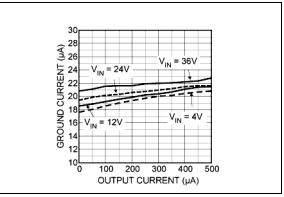


FIGURE 2-6: Ground Pin Current vs. Output Current.

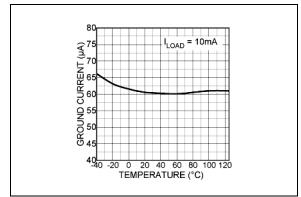


FIGURE 2-7: Ground Pin Current vs. Temperature.

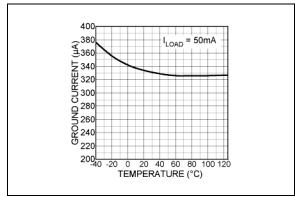


FIGURE 2-8: Temperature.

Ground Pin Current vs.

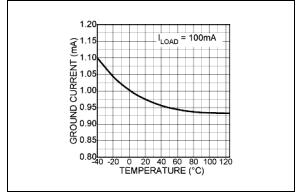


FIGURE 2-9: Ground Pin Current vs. Temperature.

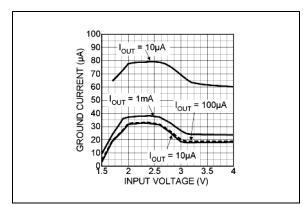


FIGURE 2-10: Ground Pin Current vs. Input Voltage.

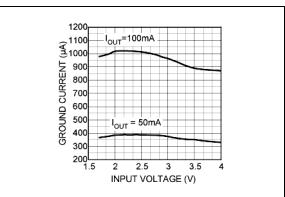


FIGURE 2-11: Ground Pin Current vs. Input Voltage.

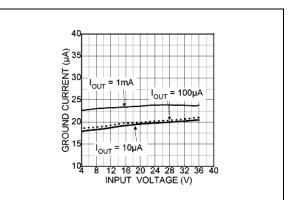


FIGURE 2-12: Ground Pin Current vs. Input Voltage.

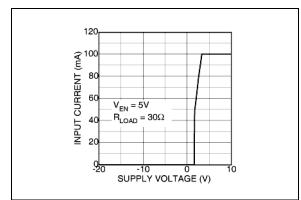


FIGURE 2-13: Input Current vs. Supply Voltage.

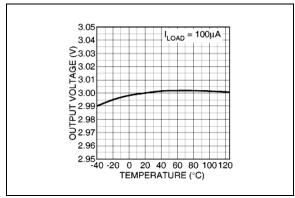


FIGURE 2-14: Output Voltage vs. *Temperature.*

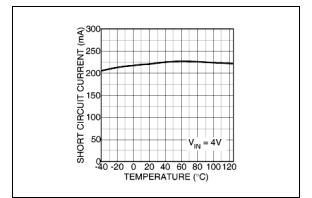


FIGURE 2-15:Short-Circuit Current vs.Temperature.

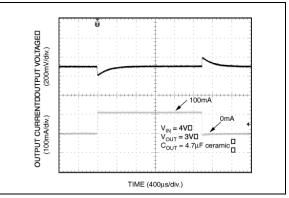


FIGURE 2-16: Load Transient Response.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

Pin Number SOT23 (M5)	Pin Name	Description		
1	NC	No Connect.		
2	GND	Ground.		
3	EN	Enable (Input). Logic Low = Shutdown; Logic High = Enable.		
4	IN	Supply Input.		
5	OUT	Regulator Output.		

4.0 APPLICATION INFORMATION

4.1 Enable/Shutdown

The MIC3490 comes with an active-high enable pin that allows the regulator to be disabled. Forcing the enable pin low disables the regulator and sends it into a "Zero" Off mode current state, consuming a typical 0.1 μ A. Forcing the enable pin high enables the output voltage.

4.2 Input Capacitor

The MIC3490 has a high input voltage capability, up to 36V. The input capacitor must be rated to sustain voltages that may be used on the input. An input capacitor may be required when the device is not near the source power supply or when supplied by a battery. Small surface mount, ceramic capacitors can be used for bypassing. A larger value may be required if the source supply has high ripple.

4.3 Output Capacitor

The MIC3490 requires an output capacitor for stability. The design requires 2.2 μF or greater on the output to maintain stability. The design is optimized for use with low-ESR ceramic chip capacitors. High-ESR capacitors may cause high-frequency oscillation. The maximum recommended ESR is 3 Ω . The output capacitor can be increased without limit. Larger valued capacitors help to improve transient response.

X7R/X5R dielectric-type ceramic capacitors are recommended because of their temperature performance. X7R-type capacitors change capacitance by 15% over their operating temperature range and are the most stable type of ceramic capacitors. Z5U and Y5V dielectric capacitors change value by as much as 50% and 60%, respectively, over their operating temperature ranges. To use a ceramic chip capacitor with Y5V dielectric, the value must be much higher than an X7R ceramic capacitor to ensure the same minimum capacitance over the equivalent operating temperature range.

4.4 No-Load Stability

The MIC3490 will remain stable and in regulation with no load, unlike many other voltage regulators. This is especially important in CMOS RAM keep-alive applications.

4.5 Thermal Consideration

The MIC3490 is designed to provide 100 mA of continuous current in a very small package. Maximum power dissipation can be calculated based on the output current and the voltage drop across the part.

To determine the maximum power dissipation of the package, use the junction-to-ambient thermal resistance of the device and Equation 4-1:

EQUATION 4-1:

$$P_{D(MAX)} = \left(\frac{T_{J(MAX)} - T_A}{\theta_{JA}}\right)$$

Where:
$$T_{J(MAX)} = Maximum junction temperature of the die at +125°C$$

	the die at + 125 C
$T_A =$	The ambient operating temperature
<i>θ</i> _{JA} =	Layout dependent

Table 4-1 shows examples of the junction-to-ambient thermal resistance for the MIC3490:

TABLE 4-1:5-PIN SOT23 THERMAL
RESISTANCE

Package	θ _{JA} Recommended Minimum Footprint		
SOT23-5	+235°C/W		

The actual power dissipation of the regulator circuit can be determined using Equation 4-2:

EQUATION 4-2:

$$P_D = (V_{IN} - V_{OUT})I_{OUT} + V_{IN} \times I_{GND}$$

Substituting $P_{D(MAX)}$ for P_D and solving for the operating conditions that are critical to the application will give the maximum operating conditions for the regulator circuit. For example, when operating the MIC3490-3.0YM5 at +50°C with a minimum footprint layout, the maximum input voltage for a set output current can be determined as follows:

EQUATION 4-3:

$$P_{D(MAX)} = \left(\frac{125 \,^{\circ}\text{C} - 50 \,^{\circ}\text{C}}{235 \,^{\circ}\text{C}/W}\right)$$

Where:

$$P_{D(MAX)}$$
 = 319 mW

The junction-to-ambient (θ_{JA}) thermal resistance for the minimum footprint is +235°C/W from Table 4-1. It is important that the maximum power dissipation not be exceeded to ensure proper operation. Because the MIC3490 was designed to operate with high input voltages, careful consideration must be given so as not to overheat the device. With very high input-to-output voltage differentials, the output current is limited by the total power dissipation.

Total power dissipation is calculated using the following equation:

EQUATION 4-4:

$$P_D = (V_{IN} - V_{OUT})I_{OUT} + V_{IN} \times I_{GND}$$

Due to the potential for input voltages up to 36V, ground current must be taken into consideration.

If we know the maximum load current, we can solve for the maximum input voltage using the maximum power dissipation calculated for a +50°C ambient, 319 mW.

EQUATION 4-5:

$$P_{D(MAX)} = (V_{IN} - V_{OUT})I_{OUT} + V_{IN} \times I_{GND}$$

 $319mW = (V_{IN} - 3V)100mA + V_{IN} \times 2.8mA$

Ground pin current is estimated using the typical characteristics of the device.

EQUATION 4-6:

$$619 \ mW = V_{IN}(102.8 \ mA)$$

Where:

 V_{IN} = 6.02V

For higher current outputs, only a lower input voltage will work for higher ambient temperatures.

Assuming a lower output current of 10 mA, the maximum input voltage can be recalculated:

EQUATION 4-7:

$$319mW = (V_{IN} - 3V)10mA + V_{IN} \times 0.1mA$$
$$349mW = V_{IN} \times 10.1mA$$

Where:

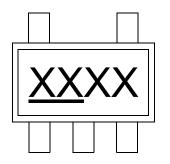
V_{IN} = 34.55V

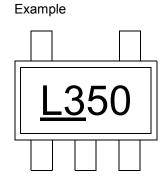
The maximum input voltage for a 10 mA load current at +50°C ambient temperature is 34.55V, utilizing virtually the entire operating voltage range of the device.

5.0 PACKAGING INFORMATION

5.1 Package Marking Information

5-Lead SOT23* (2.9x1.6 mm)





Part Number	Output Voltage	Marking Code
MIC3490-1.8YM5	1.8V	L318
MIC3490-2.5YM5	2.5V	L325
MIC3490-3.0YM5	3.0V	L330
MIC3490-3.3YM5	3.3V	L333
MIC3490-5.0YM5	5.0V	L350

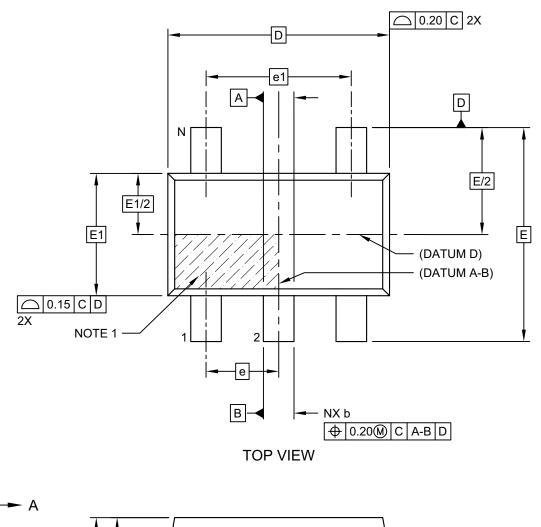
-		
Legen	Y YY WW NNN @3 *	Product code or customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC [®] designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
Note:	be carried	nt the full Microchip part number cannot be marked on one line, it will over to the next line, thus limiting the number of available characters her-specific information. Package may or may not include the corporate
	Underbar	(_) and/or Overbar (¯) symbol may not be to scale.

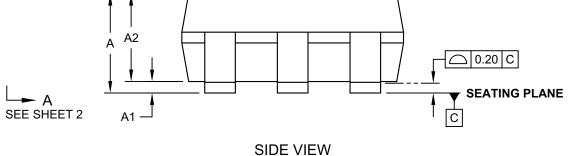
5.2 Package Details

The following sections give the technical details of the packages.

5-Lead Plastic Small Outline Transistor (OT) [SOT23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

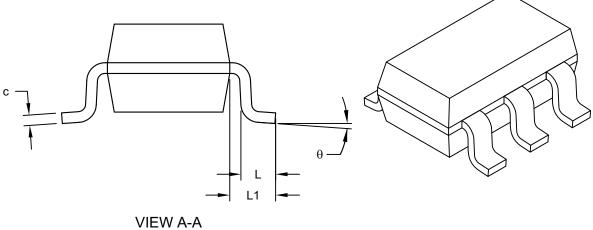




Microchip Technology Drawing C04-091-OT Rev E Sheet 1 of 2

5-Lead Plastic Small Outline Transistor (OT) [SOT23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



SHEET 1

	MILLIMETERS				
Dimension I	MIN	NOM	MAX		
Number of Pins	N		5		
Pitch	е		0.95 BSC		
Outside lead pitch	e1		1.90 BSC		
Overall Height	Α	0.90	-	1.45	
Molded Package Thickness	A2	0.89	-	1.30	
Standoff	A1	-	-	0.15	
Overall Width	E	2.80 BSC			
Molded Package Width	E1	1.60 BSC			
Overall Length	D	2.90 BSC			
Foot Length	L	0.30	-	0.60	
Footprint	L1	0.60 REF			
Foot Angle	¢	0°	-	10°	
Lead Thickness	С	0.08	-	0.26	
Lead Width	b	0.20	-	0.51	

Notes:

1. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.

2. Dimensioning and tolerancing per ASME Y14.5M

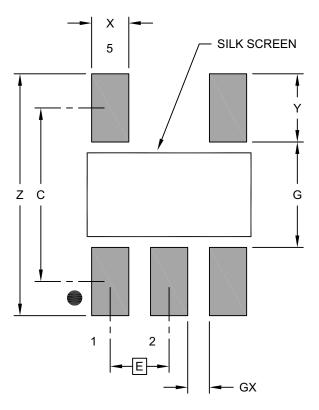
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-091-OT Rev E Sheet 2 of 2

5-Lead Plastic Small Outline Transistor (OT) [SOT23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension	Dimension Limits		NOM	MAX
Contact Pitch	E	0.95 BSC		
Contact Pad Spacing	С		2.80	
Contact Pad Width (X5)	X			0.60
Contact Pad Length (X5)	Y			1.10
Distance Between Pads	G	1.70		
Distance Between Pads	GX	0.35		
Overall Width	Z			3.90

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2091B [OT]

APPENDIX A: REVISION HISTORY

Revision A (February 2019)

Original Release of this Document

MIC3490

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.	<u>-x.x</u>	¥	<u>xxx</u>	<u>-xx</u>	Exampl	es:		
Device		Junction emperature Range	Package	Media Type	a) MIC3	490-1.8YM5-TR:	High Input Voltage, Low I _Q µCap LDO Regulator, 1.8V, -40°C to +125°C, SOT23-5, 3000/Reel	
Device:	MIC3490	•	nput Voltage,	Low I _O µCap	b) MIC3	490-2.5YM5-TR:	High Input Voltage, Low I _Q μCap LDO Regulator, 2.5V, -40°C to +125°C, SOT23-5, 3000/Reel	
	10 - 1		Regulator	Q	c) MIC3	490-3.0YM5-TR:	High Input Voltage, Low I _Q μCap LDO Regulator, 3.0V, -40°C to +125°C, SOT23-5, 3000/Reel	
	1.8 = 1 2.5 = 2 3.0 = 3	2.5V			d) MIC3	490-3.3YM5-TR:	High Input Voltage, Low I _Q µCap LDO Regulator, 3.3V, -40°C to +125°C, SOT23-5, 3000/Reel	
Output Voltage:	3.3 = 3 5.0 = 5				e) MIC3	490-5.0YM5-TR:	High Input Voltage, Low I _Q µCap LDO Regulator, 5.0V, -40°C to +125°C, SOT23-5, 3000/Reel	
Junction Temperature Ran	-	40°C to +125°C	;					
Package:	M5 =	5-Lead SOT23			Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip			
Media Type:	TR = 3	3000/Reel (SOT	23 Only)			Sales Office for package availability with the Tape and Reel option.		

MIC3490

NOTES:

Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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